10-13-2000 Docket No. JCLA5631 Form 1595 U. S. Department of Commerce **RECO** Patent and Trademark Office 101486589 To the Honorable Assistant Commissioner for Patents: Please record the attached Original documents or copy thereof. 1. Name of conveying party(ies): 2. Name/address of receiving Party(ies) MING-TSUN HSIEH VANGUARD INTERNATIONAL 3. Nature of conveyance: X Assignment SEMICONDUCTOR CORP. ☐ Merger ☐ Security Agreement ☐ Other Change of Name Reassignment 123, PARK AVE-3RD, SCIENCE-BASED INDUCTRIAL PARK, HSINCHU, TAIWAN. 4. Date(s) of execution: September 12, 2000. R.O.C. Add'l names of receiving parties Attached? Yes X No 5. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is September 12, 2000. 09670685 B. Patent No.(s) A. Patent Application No. (s) Additional numbers attached X No ? Yes 7. Total No. of applications and patents 6. Name and address of party to whom involved: correspondence concerning document should be mailed: ONE(1)8. Total fee(37CFR§ 3.41): \$40.00 J. C. Patents X Enclosed 1340 Reynolds Ave., Suite 114 Charge to Acct. No. 50-0710 Irvine, CA 92614 (Order No. JCLA5631) (949) 660-0761 9. Total number of pages, including Cover sheet, attachments and Document 3. DO NOT USE THIS SPACE 9. Statement and Signature: To the best of my knowledge and belief, the forging information is true and Correct and any attached copy is a true copy of the original document.

12/20**00** 17**H**431 00000709 09E10**685** 

Jiawei Huang 100

Name of person Signing Registration No. 43,330

Signature 9/27/00Date

## **ASSIGNMENT**



WHEREAS.

1. Ming-Tsun Hsieh

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD AND APPARATUS FOR DARK LEVEL INTEGRATION OF IMAGE SENSOR WITHOUT INTEGRATING BAD PIXELS

[ ] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Vanguard International Semiconductor Corp.
of 123, Park Ave-3rd, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor. Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

PATENT REEL: 011142 FRAME: 0504

## **ASSIGNMENT CONTINUED**

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Sole or First Joint Inventor: Ming-Tsun Hsieh

1 12 10 d Date:

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PATENT **REEL: 011142 FRAME: 0505**